

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
YU-CHUNG LIEN	06/27/2021
JIAHUI YUAN	06/26/2021
DEEPANSHU DUTTA	06/28/2021
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	SANDISK TECHNOLOGIES LLC
<b>Street Address:</b>	5080 SPECTRUM DRIVE
<b>Internal Address:</b>	SUITE 1050W
<b>City:</b>	ADDISON
<b>State/Country:</b>	TEXAS
<b>Postal Code:</b>	75001
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	17360677
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(415)489-4150
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	415-489-4100
<b>Email:</b>	wgoy@vierramagen.com
<b>Correspondent Name:</b>	RALPH F. HOPPIN
<b>Address Line 1:</b>	VIERRA MAGEN MARCUS LLP
<b>Address Line 2:</b>	2001 JUNIPERO SERRA BLVD., SUITE 515
<b>Address Line 4:</b>	DALY CITY, CALIFORNIA 94014
<b>ATTORNEY DOCKET NUMBER:</b>	SAND-02582US0
<b>NAME OF SUBMITTER:</b>	RALPH F. HOPPIN
<b>SIGNATURE:</b>	/Ralph F. Hoppin/
<b>DATE SIGNED:</b>	06/28/2021
<b>Total Attachments: 2</b>	
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**JOINT TO CORPORATE ASSIGNMENT**

WHEREAS, the undersigned:

- (1) Yu-Chung Lien, a resident of San Jose, California;  
 (2) Jiahui Yuan, a resident of Fremont, California; and  
 (3) Deepanshu Dutta, a resident of Fremont, California,  
 (collectively "INVENTORS/ASSIGNORS")

have invented subject matter ("INVENTION") disclosed and/or claimed in an application titled "BLOCK CONFIGURATION FOR MEMORY DEVICE WITH SEPARATE SUB-BLOCKS," ("APPLICATION") which:

☒ will be filed. INVENTORS/ASSIGNORS hereby authorize and request Assignee's legal representative (Ralph F. Hoppin of Vierra Magen Marcus LLP, 2001 Junipero Serra Blvd., Suite 515, Daly City, California 94014) to insert here in parentheses (filed on June 28, 2021 and given Application No. 17/360,677 by the United States Patent and Trademark Office) the filing date and application number of the Application when known.

☐ was filed on \_\_\_\_\_ and was given Application No. \_\_\_\_\_ by the United States Patent and Trademark Office.

WHEREAS SanDisk Technologies LLC (hereinafter termed "ASSIGNEE"), a limited liability company of the State of Texas, having a place of business at 5080 Spectrum Drive, Suite 1050W, Addison, TX 75001, wishes to acquire the entire right, title and interest in and to the INVENTION and the APPLICATION, and all other applications and patents derived therefrom, such as non-provisionals, continuations, and divisionals, in the United States and all other countries.

NOW THEREFORE, for good and valuable consideration acknowledged by each of the INVENTORS/ASSIGNORS to have been received in full from the ASSIGNEE:

1. The INVENTORS/ASSIGNORS do hereby sell, assign, transfer and convey to the ASSIGNEE, the entire right, title and interest (including the right of priority) (a) in and to the INVENTION and the APPLICATION; (b) in and to all rights to apply in any or all countries of the world for patents, certificates of inventions or other governmental grants on the INVENTION; (c) in and to any and all applications (including provisionals and non-provisionals) and any and all patents, certificates of inventions or other governmental grants claiming priority from the APPLICATION, such as such as non-provisional applications, continuations (in whole or in part), and divisionals in the United States and all other countries; (d) in and to each and every reissue or

extension of any of the patents referenced above; and (e) in and to each and every patent claim resulting from a reexamination certificate for any of the patents referenced above.

2. The INVENTORS/ASSIGNORS hereby jointly and severally covenant and agree to cooperate with the ASSIGNEE to enable the ASSIGNEE to enjoy to the fullest extent the right, title and interest herein conveyed in the United States and other countries. Such cooperation by the INVENTORS/ASSIGNORS shall include prompt production of pertinent facts and documents, giving of testimony, executing of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by the ASSIGNEE (a) for perfecting in the ASSIGNEE the right, title and interest herein conveyed; (b) for complying with any duty of disclosure; (c) for prosecuting any of the applications referenced above; (d) for filing and prosecuting substitute, non-provisional, divisional, continuing or additional applications covering the invention; (e) for filing and prosecuting applications for reissue of any of the patents referenced above; (f) for interference or other priority proceedings involving the INVENTION; and (g) for legal proceedings involving the INVENTION and any applications therefor and any patents granted thereon, including without limitation opposition proceedings, cancellation proceedings, priority contests, public use proceedings, reexamination proceedings, compulsory licensing proceedings, infringement actions and court actions; provided, however, that the expense incurred by the Inventors in providing such cooperation shall be paid for by the Assignee.

3. The terms and covenants of this Assignment shall inure to the benefit of the ASSIGNEE, its successors, assigns and other legal representatives, and shall be binding upon the INVENTORS/ASSIGNORS, their respective heirs, legal representatives and assigns.

4. The INVENTORS/ASSIGNORS hereby jointly and severally warrant and represent that they have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

5. The INVENTORS/ASSIGNORS hereby jointly and severally consent to, covenant and agree that electronic signatures appearing on this agreement are the same as handwritten signatures for the purposes of validity, enforceability and admissibility.

Date: 6/27/2021 | 9:57 PM PDT

(1)

DocuSigned by:  
*Yu-Chung Lien*  
773520E937104A7...  
Yu-Chung Lien

Date: 6/26/2021 | 11:07 AM PDT

(2)

DocuSigned by:  
*Jiahui Yuan*  
B6ED30F1F9FB495...  
Jiahui Yuan

Date: 6/28/2021 | 8:12 AM PDT

(3)

DocuSigned by:  
*Deepanshu Dutta*  
14791D1BE681468...  
Deepanshu Dutta